

產品承認書/規格書

CUSTOMER.		DATE: 2009/09/22
MESSRS.	佳得股份有限公司	SUBMIT NO. WH09092202

Product Specification/Approval Sheet

PART TYPE: TDK POWER INDUCTORS

CUST. P/N	l:
ΓDK P/N:	SLF12575T-220M4R0-PF
	本承認書內容若貴公司確認無誤,懇請於下方承認欄內簽章寄回
	Please confirm your acceptance of this approval sheet by return fax.

台北市內湖區 114 洲子街 102 號 3F 3F., NO.102, CHOW TZE STREET. NEI-HU WARD 114,TAIPEI, TAIWAN,R.O.C.

TEL NO. (02)2657-5178

FAX NO.(02)2657-5173

單位主管	業務擔當
	業務部 2009.09.22 黃英全

文浩實業 承認書 INDEX

(系	列)承認品名:ve	endor:	(文浩)
項次	項目	頁次	備註
1	符合 RoHS 第三驗認證單位測試報告	另附	
2	零件尺寸圖	5	
3	零件電氣特性及詳細使用規格	6	
4	零件材質說明	5	
5	零件使用規範注意事項	7~10	
6	零件 SMT 製程參數(REFLOW 曲線圖)	10	
7	零件包裝方式說明	11~12	



TDK TAIWAN CORPORATION

6TH FL., 260 TUN HWA N. RD., TAIPEI, TAIWAN, REPUBLIC OF CHINA

TEL: 02-27125090 FAX: 02-27123090 **公TDK**。

TDK XIAMEN CO., LTD.

321 TONGJI SOUTH ROAD, JIMEI DISTRICT, XIAMEN, FUJIAN, CHINA (361021)

TEL: 0592-6150338 FAX: 0592-6150320

PRODUCT SPECIFICATION

or

		SPEC. NO : CA14294A
WIN-HOUSE CO., 1	LTD.	DATE: SEP. 12, 2005
CUSTOMER'S PRODUCT NAME:		
TDK PRODUCT NAME:		
	SLF12575T-TYPE-PF	
THIS SPECIFICATION IS:		
☐ FULLY ACCEPTED		
☐ DENIED		
ACCEPTED UNDER THE FO	TOWING CONDITIONS	
ACCEPTED UNDER THE FOR	LLOWING CONDITIONS	
	O LON LATINE	DATE
	SIGNATURE:	DATE:
	NAME(PRINT):	
	TITLE:	

ELECTRONIC COMPONENTS DIV.

COIL & TRANSFORMER MFG. DEPT.

FACTORY:

159 SEC. 1 CHUNG SHAN N. RD., TATUNG LI, YANG MEI, TAOYUAN, TAIWAN, REPUBLIC OF CHINA

TEL: 03-4784111 FAX: 03-4757322

ELECTRONIC COMPONENTS DIV.

COIL & TRANSFORMER MFG. DEPT.

FACTORY:

or

321 TONGJI SOUTH ROAD, JIMEI DISTRICT, XIAMEN, FUJIAN, CHINA (361021)

TEL: 0592-6150338 FAX: 0592-6150322

TDK PT/NO:

SLF12575T-TYPE-PF

SPEC. NO.

CA14294A

I . SCOPE:

This specification applies to the high current type SMD inductors for SLF12575T-. $\bigcirc\bigcirc\bigcirc\bigcirc\triangle\triangle\triangle$ -PF

 Π . INDEX:

LISTED ITEM	ATTACHEMENT & TABLES	PAGE
1. SHAPES AND DIMENSIONS	Please see (1)	2/9
2. ELECTRICAL SPECIFICATIONS	Please see (2)	2/9 , 3/9
3. CHARACTERISTICS	Please see (3)	2/9
4. ELECTRICAL SCHEMATICS	Please see (4)	3/9
5. RELIABILITY TEST METHOD	Please see (5)	4/9 , 5/9 , 6/9
6. LAND DIMENSION (Ref.)	Please see (6)	7/9
7. PACKAGING	Please see (7)	8/9,9/9

8. TANDARD TEST CONDITIONS

Unless otherwise specified, test condition should be Temp. = $20\pm15^{\circ}$ C, Humidity= $35\sim85\%$

But if needed, then test condition should be Temp. = $20\pm2^{\circ}$ C, Humidity= $65\pm5\%$

III. MANUFACTURING LOCATION

- 1) YANGMEI in TAIWAN
- 2) XIAMEN in CHINA

APPROVED BY

ABB. 17. 2003

CHECKED BY

chem Ed. 1 mes

Feb, 14, >00.

MADE BY Zo

Feb. 14, 2003

TDK PT/NO:

SPEC. NO.

SLF12575T-TYPE-PF

A: 12.5 ± 0.2

B: 12.5 ± 0.2

 $C: 7.5\pm0.34$

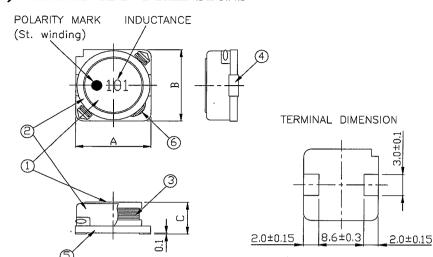
CA14294A

m/m

m/m

m/m

(1) SHAPES AND DIMENSIONS



(2) ELECTRICAL SPECIFICATIONS

SEE TABLE 1

TEST INSTRUMENTS

L : HP 4284A PRECISION LCR METER (or equivalent)

RDC: AD-5812 DIGITAL LOW-OHMMETER (or equivalent)

(3) CHARACTERISTICS

- (3)-1 Temperature rise $\dots +40^{\circ}$ C Max.
- (3)-2 Ambient temperature +65°C Max.
- (3)-3 Operate temperature range $-20^{\circ}\text{C} \sim +105^{\circ}\text{C}$ (Including self temp. rise)
- (3)-4 Storage temperature range $-40^{\circ}\text{C} \sim +105^{\circ}\text{C}$

MATERIALS

NO.	ITEM	DESCRIPTION & TYPE	UL NO.	MANUFACTURER
1	DR CORE	FERRITE		TDK CORP.
2	RING CORE	FERRITE		TDK CORP.
3	WIRE	POLYURETHANE ENAMELLED	E174837	JUNG SHING WIRE CO., LTD.
		COPPER WIRE	E169536	HUI HONG WRIE CO., LTD.
			E164823	FLOODLIT ENTERPRISE CO., LTD.
			E189722	SALOM ELECTRIC (XIAMEN) CO., LTD.
4	TERMINAL	SOLDER PLATED		SAKURAMOTO
5	BASE	PHENOLIC RESIN PM-9820	E41429	SUMITOMO BAKELITE CO., LTD.
6	ADHESIVE	EPOXY RESIN		SHAW HUOW ENTERPRISE CO., LTD.
		(BLUE or GRAY)		SHIKOKU

TDK PT/NO:

SLF12575T-TYPE-PF

SPEC. NO.

CA14294A

TABLE

خاتار			•			
		"	RESISTANCE	RATED DO	CURRENT	
TDK PT/NO.	INDUCTANCE	TEST FREQ.	$RDC(\Omega)$	Irat	(A)	MARKING
SLF12575T-	L(μH)	OF L	Max	IDC1(A)	IDC2(A)	
1R2M8R2-PF	1.2±30%	1 KHz,1V	8.3m	13	8.2	●1R2
2R7N7R0-PF	2.7±30%	<i>II</i>	11.3m	10	7.0	●2R7
3R9N6R7-PF	3.9±30%	//	12.5m	9.0	6.7	●3R9
4R7N6R5-PF	4.7±30%	<i>//</i>	13.2m	8.4	6.5	●4R7
5R6M6R3-PF	5.6±20%	//	13.9m	7.8	6.3	●5R6
5R6N6R3-PF	5.6±20%	<i>II</i>	13.9m	7.8	6.3	●5R6
6R8M5R9-PF	6.8±20%	<i>II</i>	15.7m	7.2	5.9	●6R8
6R8N5R9-PF	6.8±30%	<i>II</i>	15.7m	7.2	5.9	●6R8
100M5R4-PF	10±20%	<i>II</i>	18.7m	5.5	5.4	●100
120M5R1-PF	12±20%	<i>"</i>	20.4m	5.1	5.2	●120
150M4R7-PF	15±20%	<i>"</i>	22. 1m	4.7	5.0	●150
220M4R0-PF	22±20%	<i>!</i> /	31.6m	4.0	4.0	●220
330M3R2-PF	33±20%	<i>"</i>	47.4m	3.2	3.4	●330
470M2R7-PF	47±20%	<i>"</i>	63. 4m	2.7	3.0	● 470
680M2R0-PF	68±20%	<i>"</i>	93. 4m	2.0	2.4	●680
101M1R9-PF	100±20%	<i>"</i>	0.15	1.9	1.9	●101
151M1R5-PF	150±20%	<i>"</i>	0. 21	1.5	1.6	● 151
221M1R3-PF	220±20%	//	0.31	1.3	1.3	●221
331M1RO-PF	330±20%	//	0.41	1.0	1.1	●331
471MR80-PF	470±20%	//	0.72	0.8	0.8	● 471
681MR70-PF	680±20%	//	1.02	0.7	0.7	●681

% IDC1: BASED ON INDUCTANCE CHANGE (△L/Lo: \le -15%)

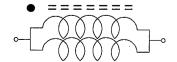
IDC2: BASED ON TEMPERATURE RISE ($\triangle T$: 40°C TYP.)

RATED DC CURRENT: THE LESS VALUE WHITH IS IDC1 OR IDC2

(4) ELECTRICAL SCHEMATICS

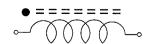
(4)-1 1.2 μ H \sim 68 μ H

St. side



(4)-2 $100 \mu \text{H} \sim 220 \mu \text{H}$

St. side



TDK PT/NO:

SLF12575T-TYPE-PF

SPEC. NO.

PF CA14294A

(5) RELIABILITY TEST METHOD

MECHANICAL.

MECHANICAL		
TEST ITEM	SPECIFICATION	TEST DETAILS
Substrate bending	△L/Lo≦±5%	The sample shall be soldered onto the printed
		circuit board in figure 1 and a load applied
	There shall be	unitil the figure in the arrow direction is made
	no mechanical	approximately 3mm.(keep time 30 seconds)
	damage or elec-	PCB dimension shall the page 7/9
	trical damege.	
		F(Pressurization)
		\Box
		R5 45±2 45±2
		PRESSURE ROD
		figure-1
Vibration	△L/Lo≦±5%	The sample shall be soldered onto the printed
		circuit board and when a vibration having an
	There shall be	amplitude of 1.52mm and a frequency of from
	no mechanical	10 to 55Hz/1 minute repeated should be applied
	damage.	to the 3 directions (X,Y,Z) for 2 hours each.
		(A total of 6 hours)
Solderability		Flux (rosin (JIS-K-5902), isopropyl alcohol
		[JIS-K-1522]) shall be coated over the whole
		of the sample before hard, the sample shall then
		be preheated for about 2 minutes in a temperature
		of $130\sim150^{\circ}\text{C}$ and after it has been immersed to a
		depth 1.0mm below for 3±1 seconds fully in molten
		solder H63A (JIS-Z-3282) with a temperature of
		230±5°C. More than 90% of the electrode sections
		shall be couered with new solder smoothly when
		the sample is taken out of the solder bath.

TDK PT/NO: SLF12575T-TYPE-PF SPEC. NO.

CA14294A

MECHANICAL

MECHANICAL		
TEST ITEM	SPECIFICATION	TEST DETAILS
Resistance to Soldering heat	There shall be no damage or	Temperature profile of reflow soldering
(reflow soldering)	_	Soldering (Peak temperature 260±3°C 10 sec 250 Pre-heating Slow cooling (Stored at room temperature) 2 min 2 min 10 2 min 10 2 min. or more
		The specimen shall be passed through the reflow oven with the condition shown in the above profile for 1 time. The specimen shall be stored at standard atmospheric conditions for 1 hour, after which the measurement shall be made.

ELECTRICAL

ELECTRICAL		
TEST ITEM	SPECIFICATION	TEST DETAILS
Insulation	There shall be	DC 100V voltage shall be applied across this sam-
resistance	no other	ple of top surface and the terminal.
	damage or	The insulation resistance shall be more than
	problems.	$1 \times 10^8 \Omega$.
Dielectric	There shall be	AC 100V voltage shall be applied for 1 minute
withstand	no other	acrosset the top surface and the terminal of this
voltage	damage or	sample
	problems.	
Temperature	△L/L20℃ ≦±10%	The test shall be performed after the sample has
characteristics	0~2000 ppm/°C	stabilized in an ambient temperature of -20 to
		+85% ,and the value calculated based on the value
		applicable in a normal temperature and narmal
		humidity shall be △L/L20℃≤±10%.
		Measurement Equipments:
		HP IMPEDANCE ANALYZER (at 10 KHz)

TDK PT/NO:

SLF12575T-TYPE-PF

SPEC. NO.

CA14294A

ENVIROMENT CHARACTERISTICS

ENVIROMENT CHARACTERISTICS					
TEST ITEM	SPECIFICATION	TEST DETAILS			
High temperature	△L/Lo≦±5%	The sample shall be left for 96±4 hours in an			
storage		atmospere with a temperature of 85±2°C and a nor-			
	There shall be	mal humidity. Upon completion of the measurement			
	no mechanical	shall be made after the sample has been left in			
	damage.	a normal temperature and normal humidity for 1			
		hour.			
Low temperature	△L/Lo≦±5%	The sample shall be left for 96±4 hours in an			
storage		atmosphere with a temperature of $-25\pm3^{\circ}\mathrm{C}$. Upon			
	There shall be	completion of the test, the measurement shall be			
	no mechanical	made after the sample has been left in a normal			
	damage.	temperature and normal humidity for 1 hour.			
Change of	△L/Lo≦±5%	The sample shall be subject to 5 continuos cycles,			
temperature		such as shown in the table 2 below and then it			
	There shall be	shall be subjected to standard stmospheric condi-			
	no other dama-	tions for 1 hour, after which measurement shall			
	ge of problems	be made.			
		table 2			
		Temperature Duration			
		1 −25±3°C 30 min.			
		(Themostat No.1)			
		Standard 5 sec. or less			
		atmospheric No.1→No.2			
		3 85±2°C 30 min.			
		(Themostat No.2)			
		Standard 5 sec. or less			
		atmospheric No.2→No.1			
Moisuture storage	△L/Lo≦±5%	The sample shall be left for 96±4 hours in a tem-			
		perature of 40±2°C and a humidity(RH) of 90~95%.			
	There shall be	Upon completion of the test, the measurement shall			
	no mechanical	be made after the sample has been left in a normal			
	damage.	temperature and normal humidity more than 1 hour.			
Test conditions:	<u>.</u>				
	The sample shall be reflow soldered onto the printed circuit board				
in every test.					

TDK PT/NO:

SLF12575T-TYPE-PF

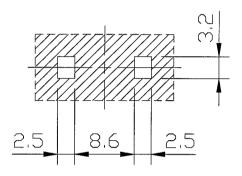
SPEC. NO.

CA14294A

(6) LAND DIMENSION (Ref.)

PCB: GLASS EPOXY t = 1.6mm

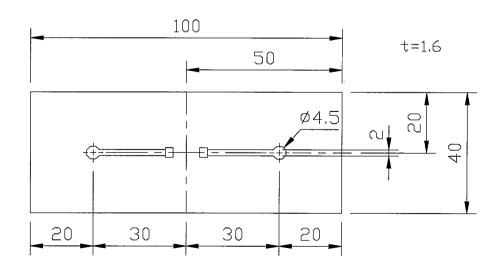
(6)-1 LAND PATTERN DIMENSIONS (STANDARD PATTERN)



Solder resist Copper foil (0.035mm)

screen: $150 \mu \text{m}$ to $200 \mu \text{m}$

(6)-2 SUBSTRATE BENDING TEST BENDING TEST BOARD



TDK PT/NO:

SLF12575T-TYPE-PF

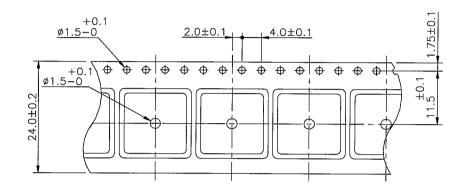
SPEC. NO.

CA14294A

(7) PACKAGING

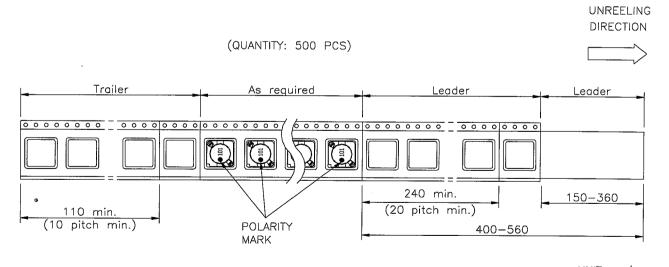
(PACKAGING FORMAT: EIAJ-RC-1009B)

(7)-1 CARRIER TAPE DIMENSIONS



CUMULATIVE
20 PITCH 80±0.15

(7)-2 TAPING DIMENSIONS



UNIT: m/m

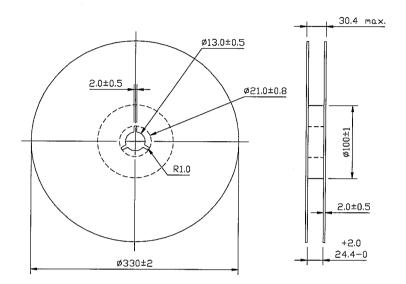
TDK PT/NO:

SLF12575T-TYPE-PF

SPEC. NO. CA14294A

(7)-3 REEL DIMENSIONS

(REEL DIMENSIONS: EIAJ-RC-1009B)



(7)-4 QUANTITY

500pcs/Reel

(7)-5 OUTER BOX

4 Reel/Box

Box size: $350\times350\times130$

(7)-6 MARKING

The following items shall be marked each unit pack.

Customer

Insp. no.

Customer pt/no.

Date

 $L(\mu H)$ & Tol.

Lot no.

TDK Item no.

Quantity

TDK pt/no.

(7)-7 The products are packaged so that no damage will be sustained.